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United States Patent [19]

Mizukami

[11] **Patent Number: Des. 424,583**

[45] **Date of Patent: ** May 9, 2000**

[54] **HINGE UNIT FOR VACUUM-PROCESSING A SEMICONDUCTOR WAFER**

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[73] Assignee: **Tokyo Electron Limited**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/086,850**

[22] Filed: **Apr. 21, 1998**

[30] **Foreign Application Priority Data**

Oct. 21, 1997 [JP] Japan 9-72009

[51] **LOC (7) Cl.** **15-09**

[52] **U.S. Cl.** **D15/122**; D8/323; D15/138; D15/141

[58] **Field of Search** D13/182; 414/217, 414/935, 937; 16/221, 244, 354; 49/149, 152, 153, 246, 247, 254; D15/122, 138, 141; D8/323

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a hinge unit for vacuum-processing a semiconductor wafer, as shown.

DESCRIPTION

FIG. **1** is a front elevational view of hinge unit for vacuum-processing a semiconductor wafer, showing my new design;

FIG. **2** is a top plan view thereof;

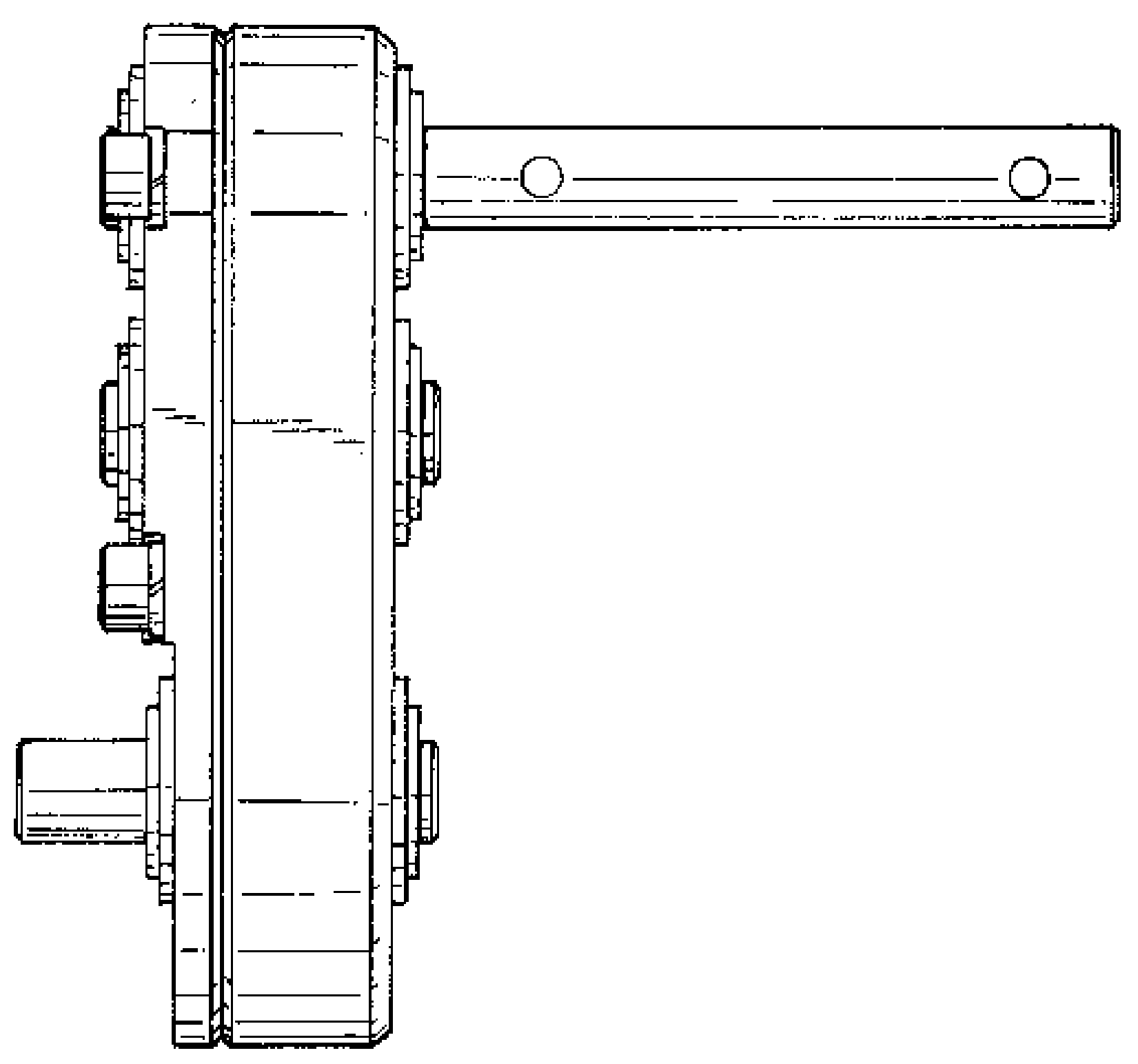
FIG. **3** is a bottom plan view thereof;

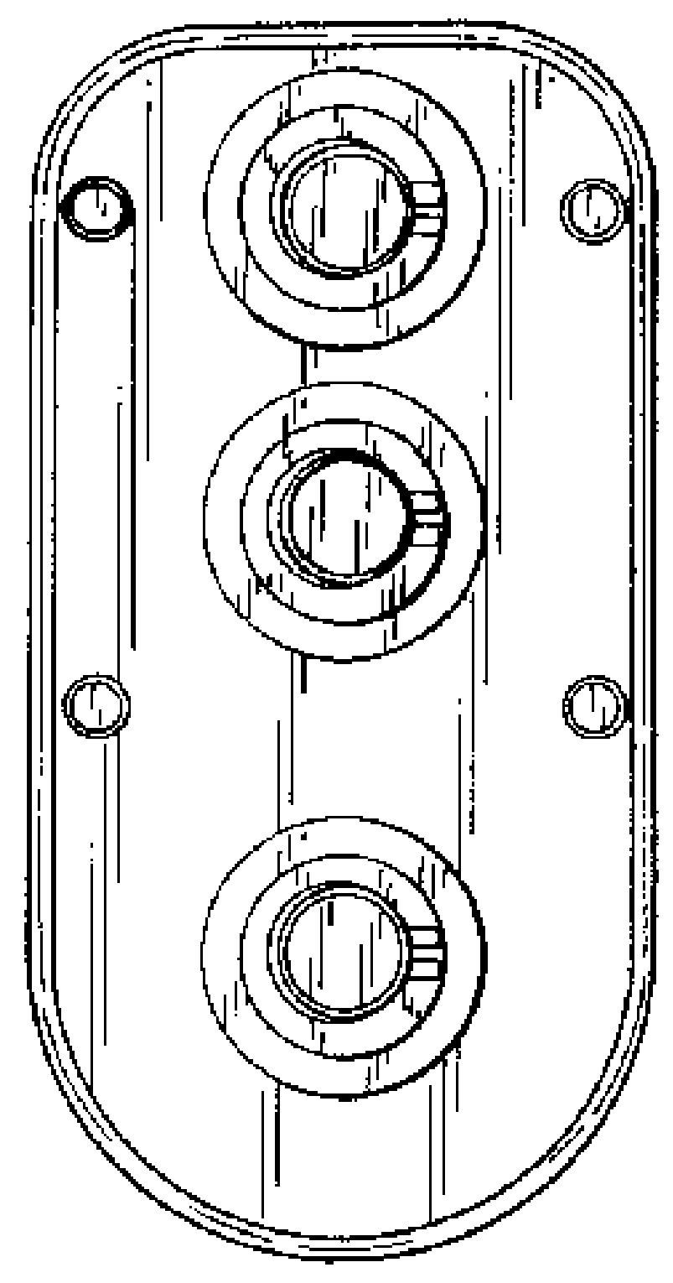
FIG. **4** is a right side elevational view thereof;

FIG. **5** is a rear elevational view thereof; and,

FIG. **6** is a left side elevational view thereof.

1 Claim, 2 Drawing Sheets





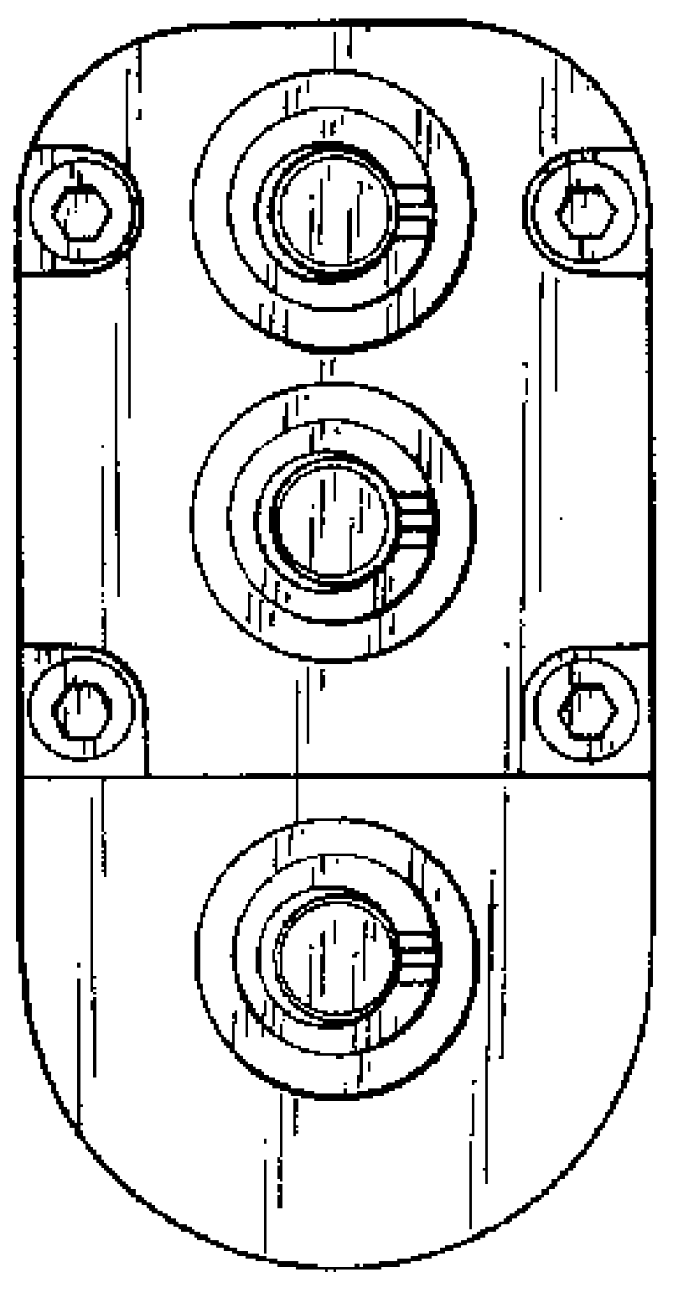


FIG. 2

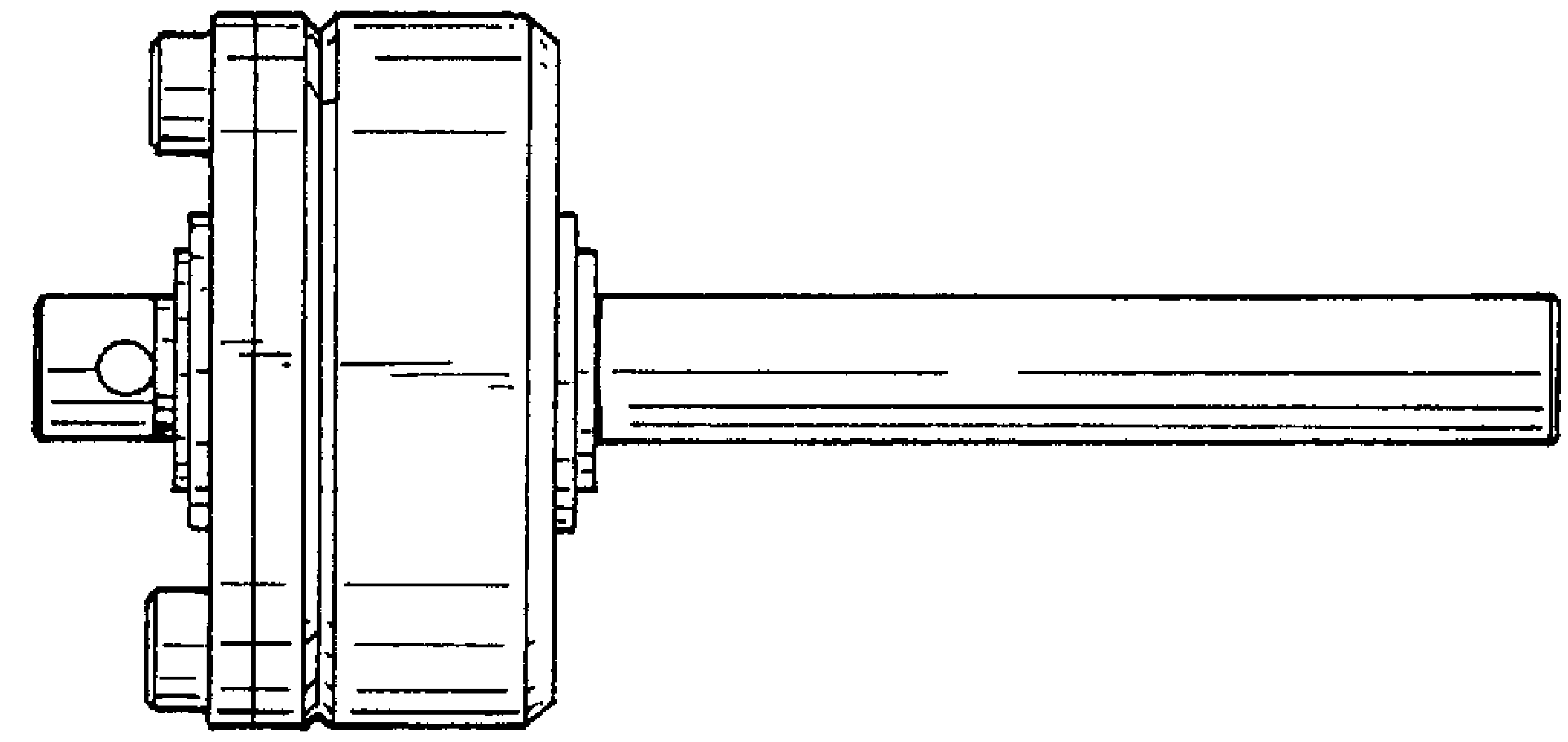


FIG. 1

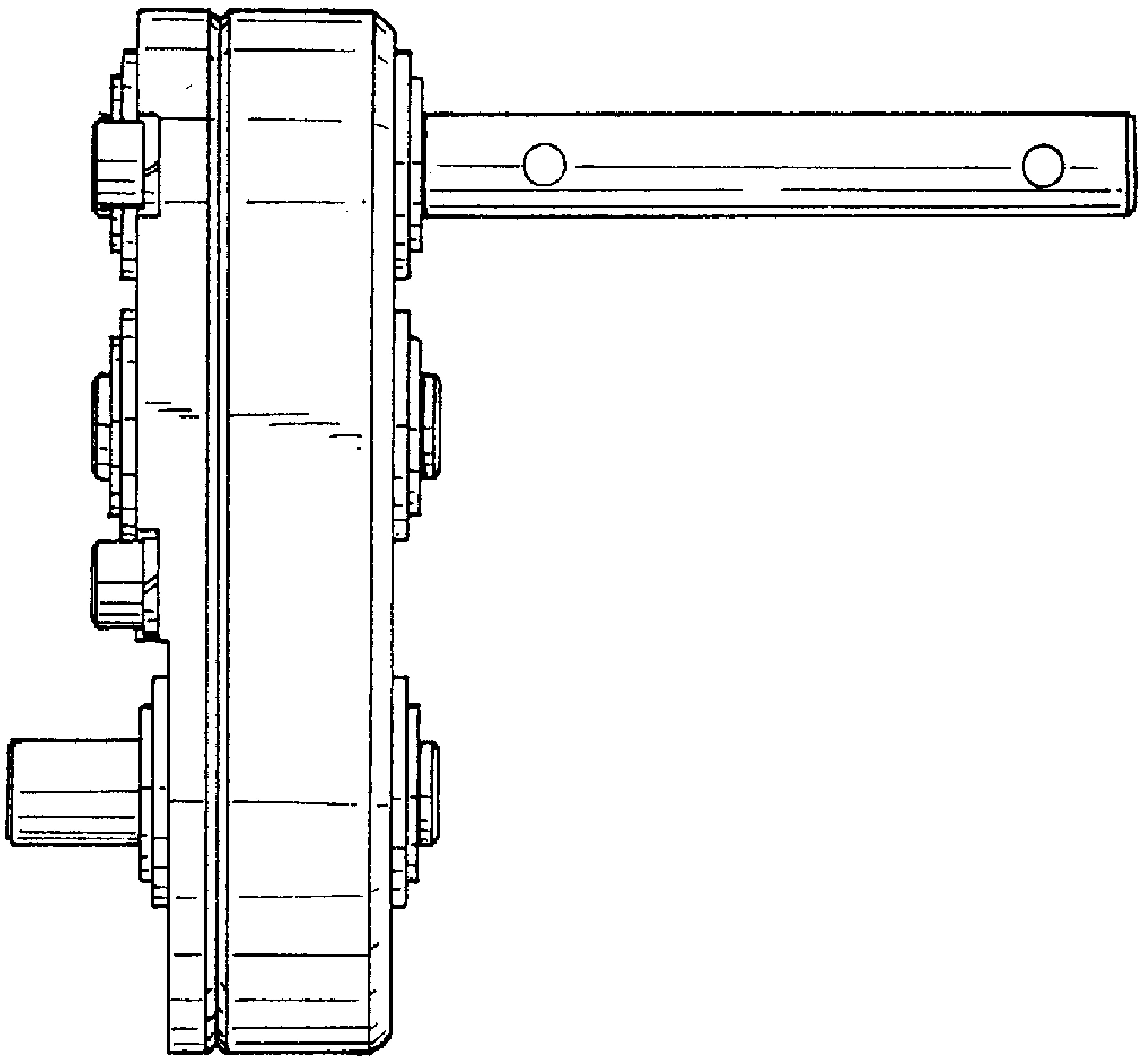


FIG. 4

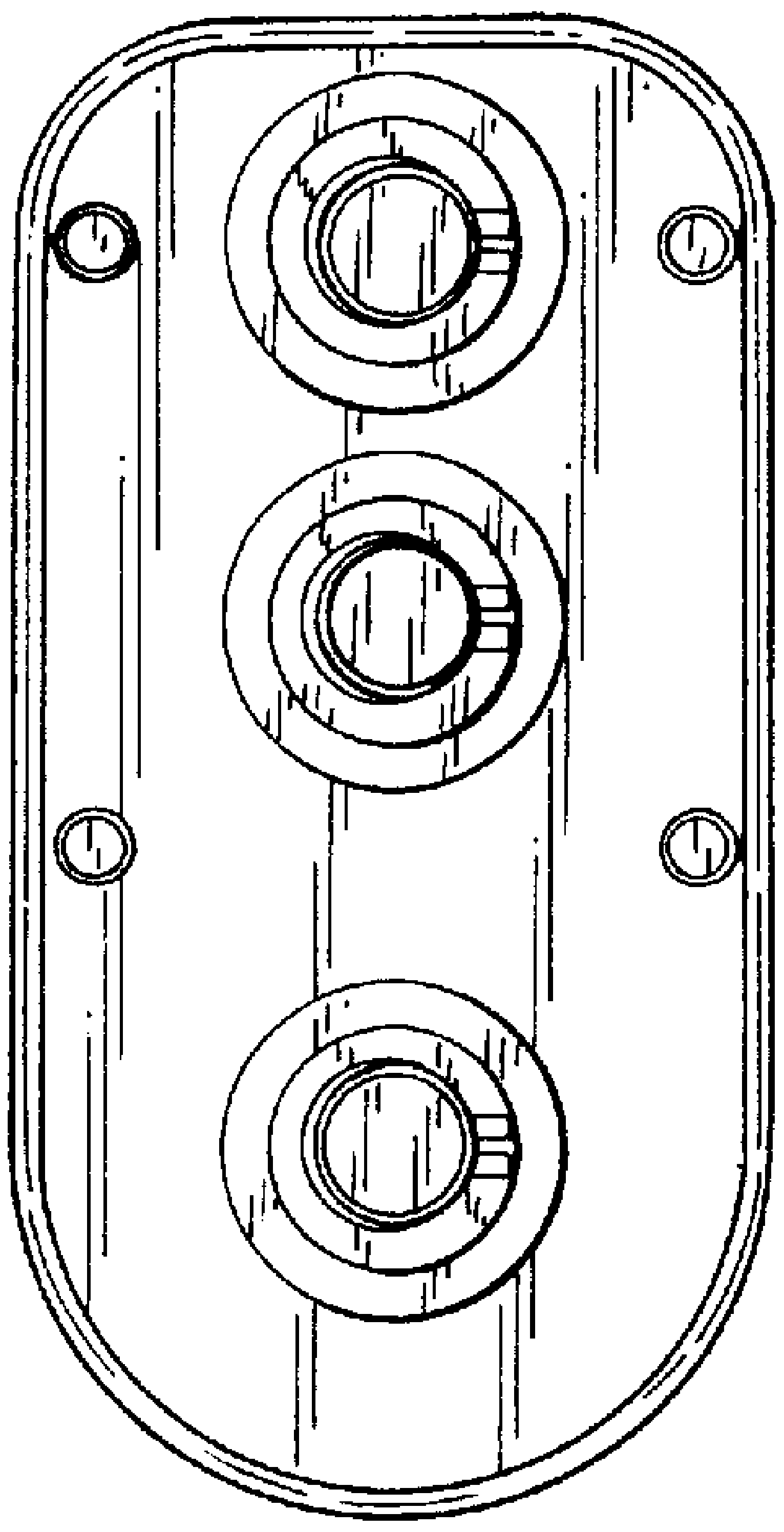


FIG. 3

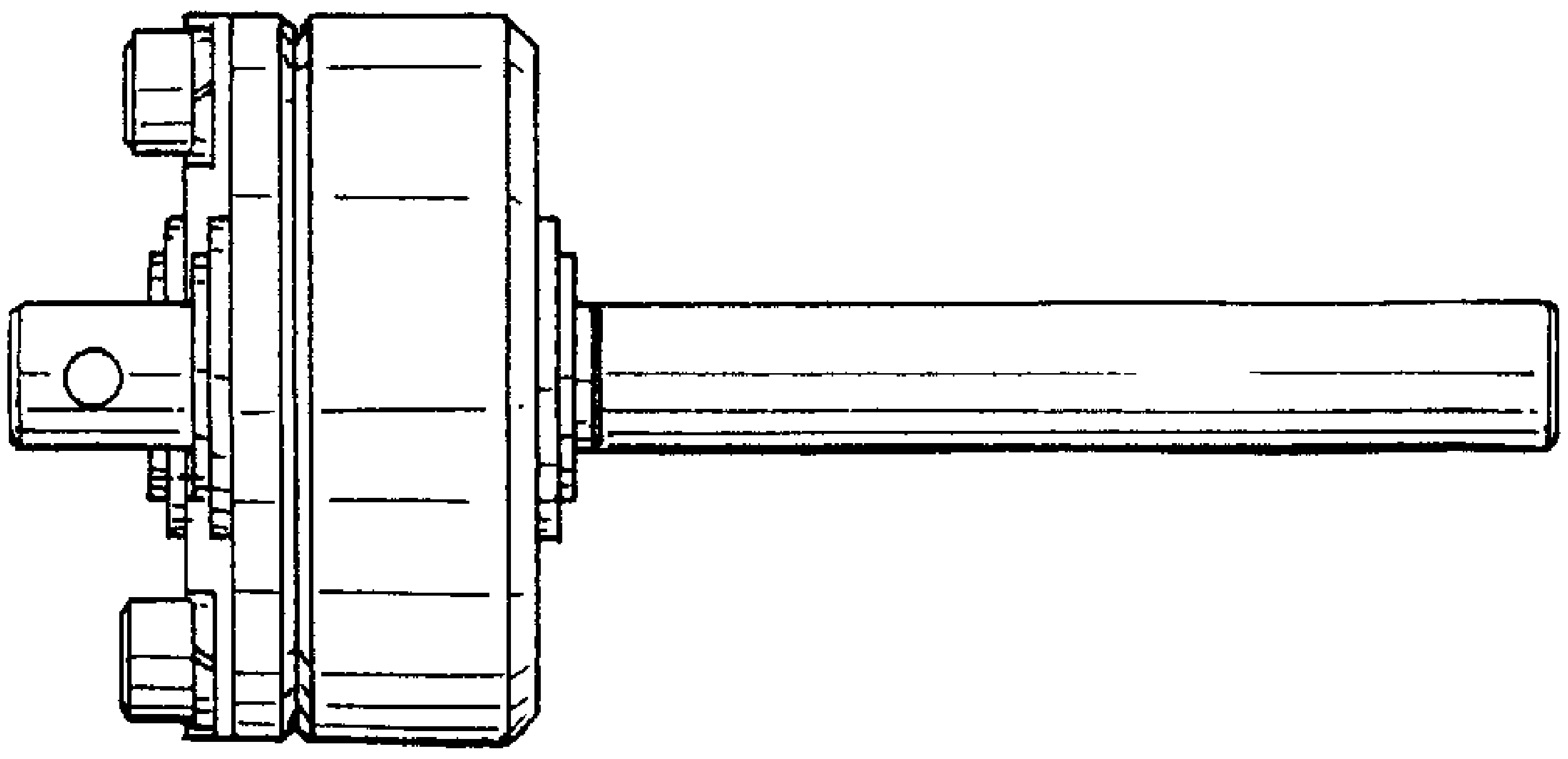


FIG. 5

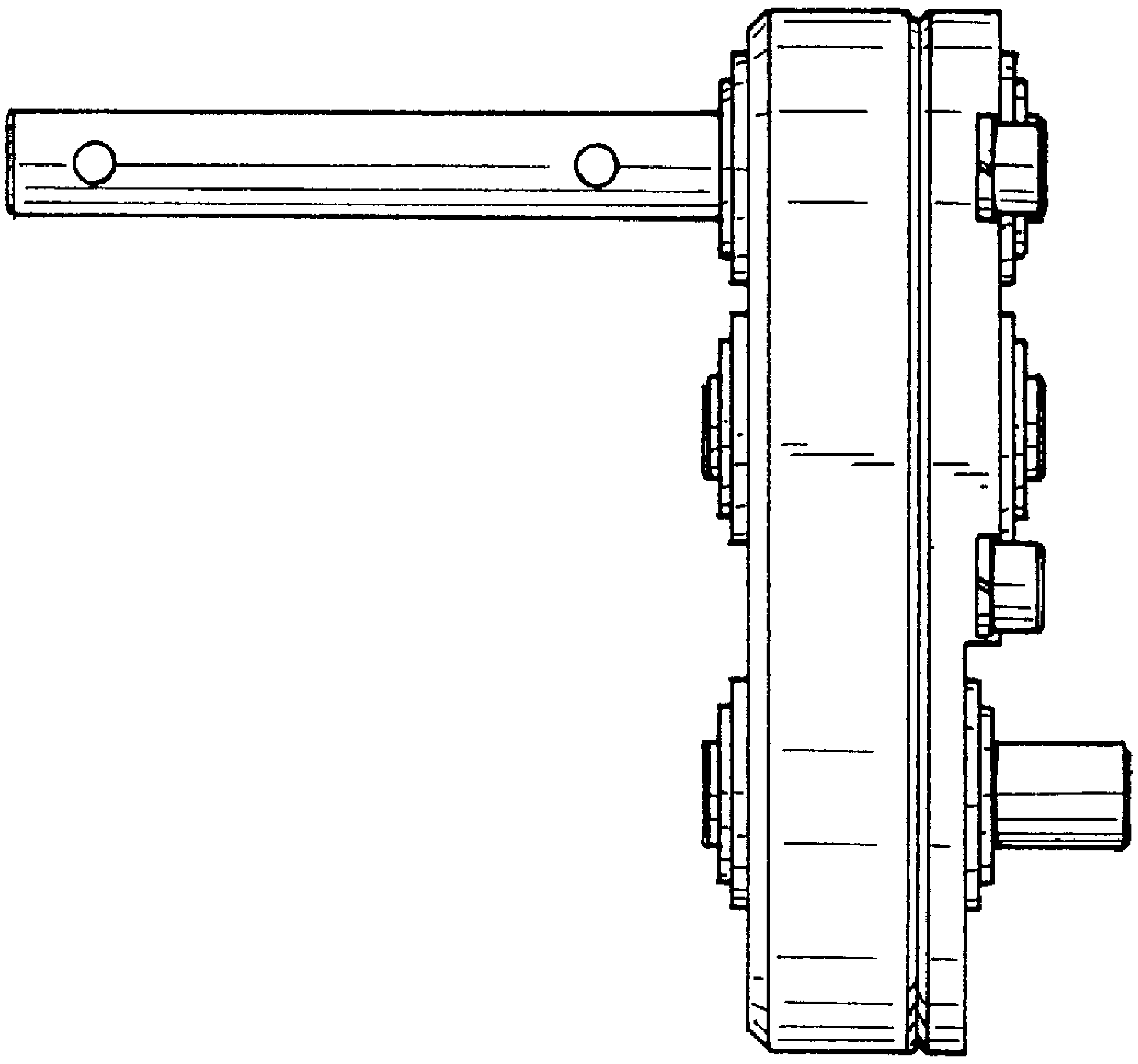


FIG. 6